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(12) **United States Design Patent**
Shentu et al.

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(54) **INTERCONNECTING DEVICE FOR THERMAL MANAGEMENT SYSTEM**

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(**) Term: **15 Years**

(21) Appl. No.: **29/631,095**

(22) Filed: **Dec. 27, 2017**

(30) **Foreign Application Priority Data**

Jun. 29, 2017 (CN) 2017 3 0280059

(51) **LOC (12) Cl.** **15-05**

(52) **U.S. Cl.**
USPC **D15/5**

(58) **Field of Classification Search**
USPC D10/46; D15/5; D23/233, 235
CPC F01P 3/14; F01P 2007/146; F01P 1/08; F02M 3/045; F02M 3/09; F02M 9/10; F02M 9/103; F02M 9/106; F02M 19/00; F02M 21/023; F02M 21/0257; F02M 23/006
See application file for complete search history.

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123/41.72

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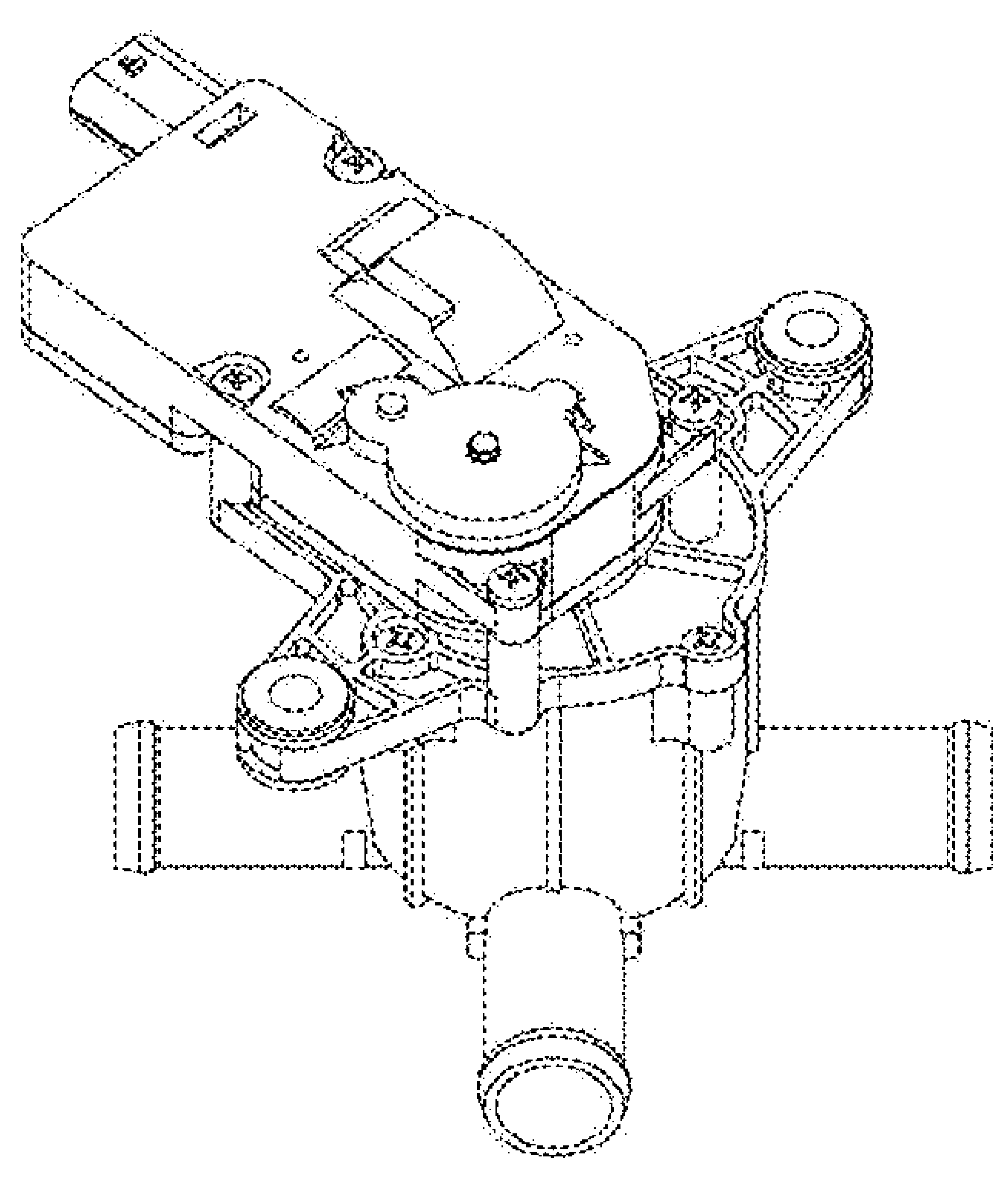
(57) **CLAIM**

The ornamental design for an interconnecting device for thermal management system, as shown and described.

DESCRIPTION

FIG. **1** is a front view of an interconnecting device for thermal management system according to the present application;
FIG. **2** is a rear view of the interconnecting device for thermal management system according to the present application;
FIG. **3** is a left view of the interconnecting device for thermal management system according to the present application;
FIG. **4** is a right view of the interconnecting device for thermal management system according to the present application;
FIG. **5** is a top view of the interconnecting device for thermal management system according to the present application;
FIG. **6** is a bottom view of the interconnecting device for thermal management system according to the present application; and,
FIG. **7** is a perspective view of the interconnecting device for thermal management system according to the present application.
The broken lines depict portions of the interconnecting device for thermal management system that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



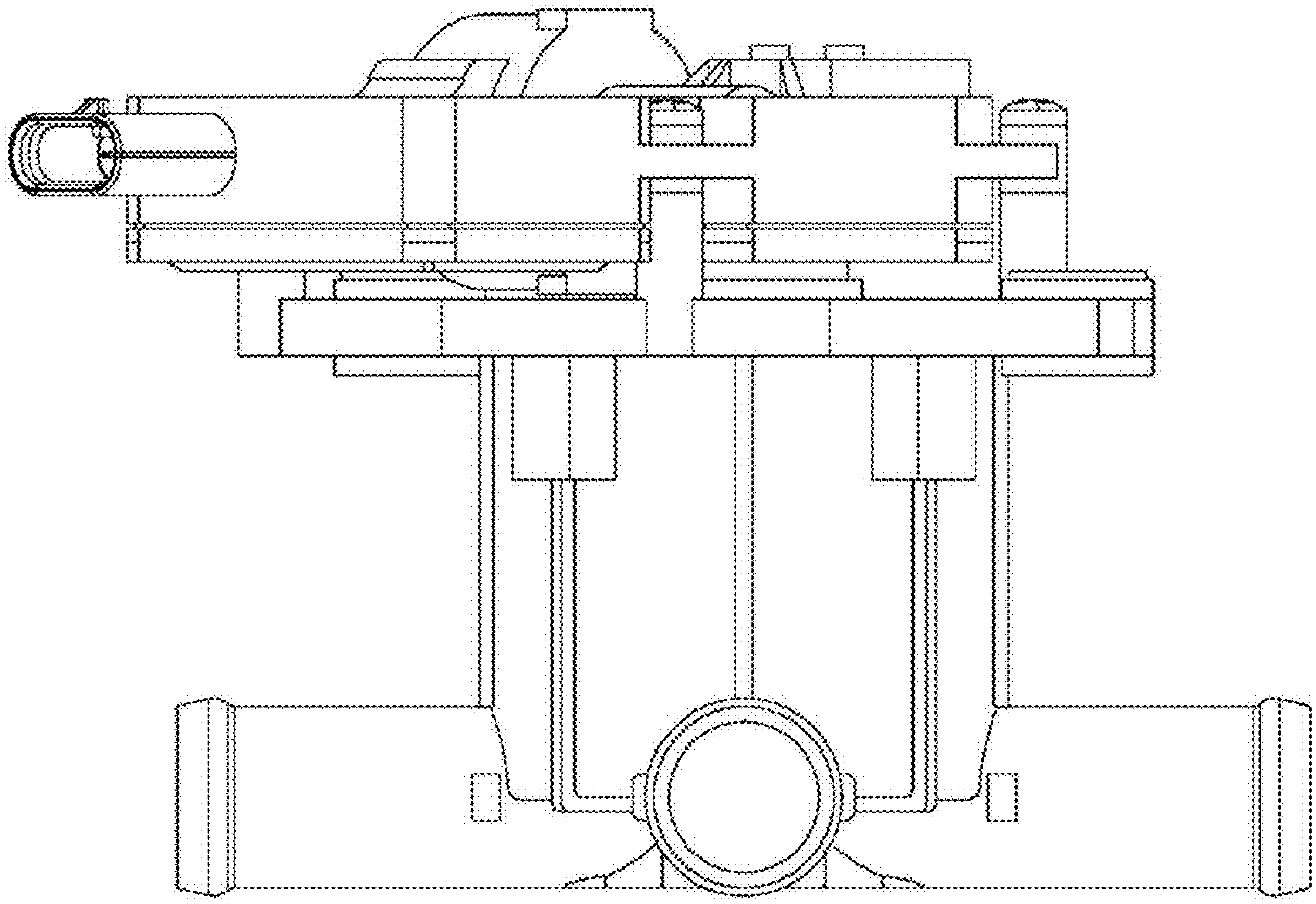


Fig. 1

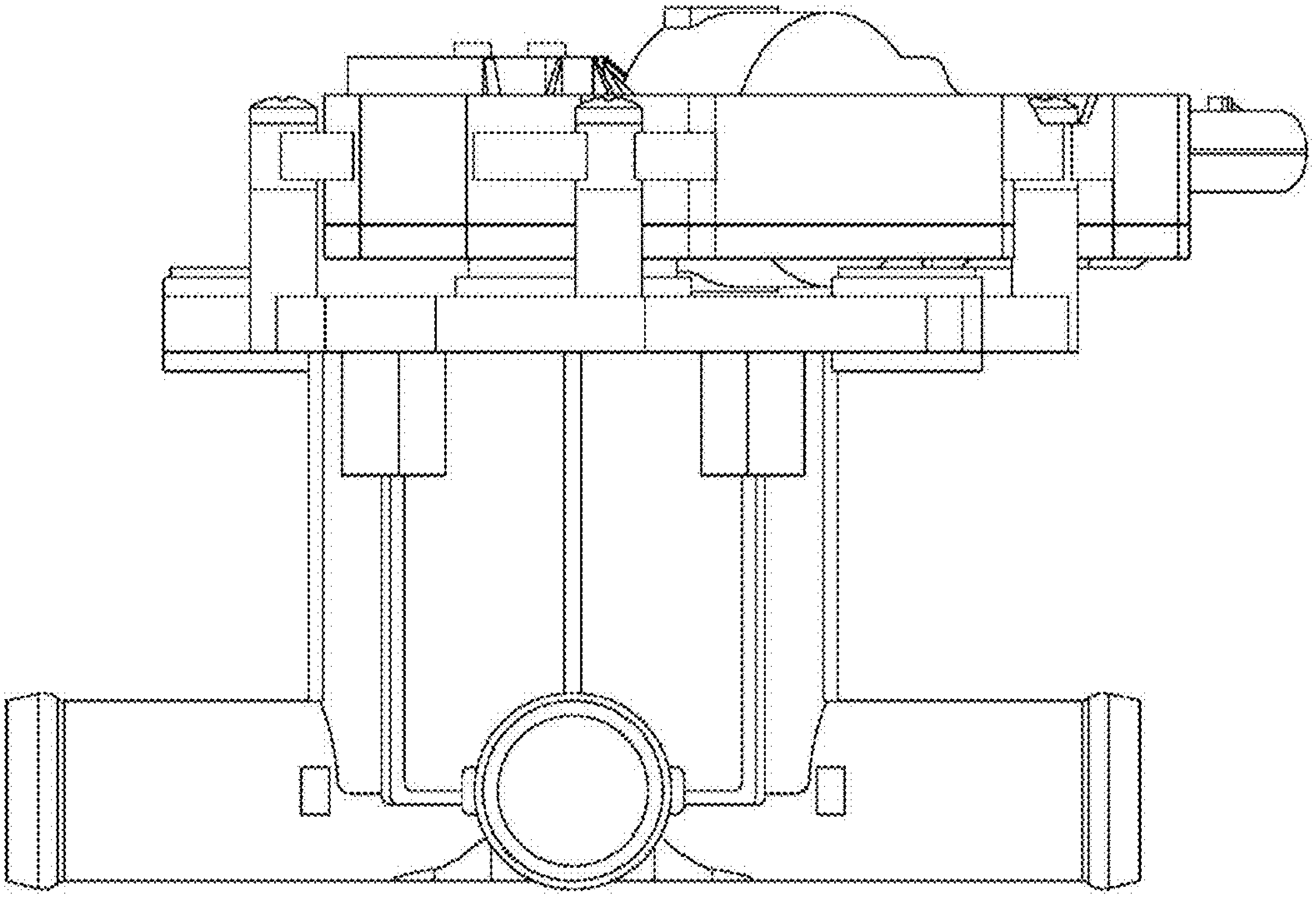


Fig. 2

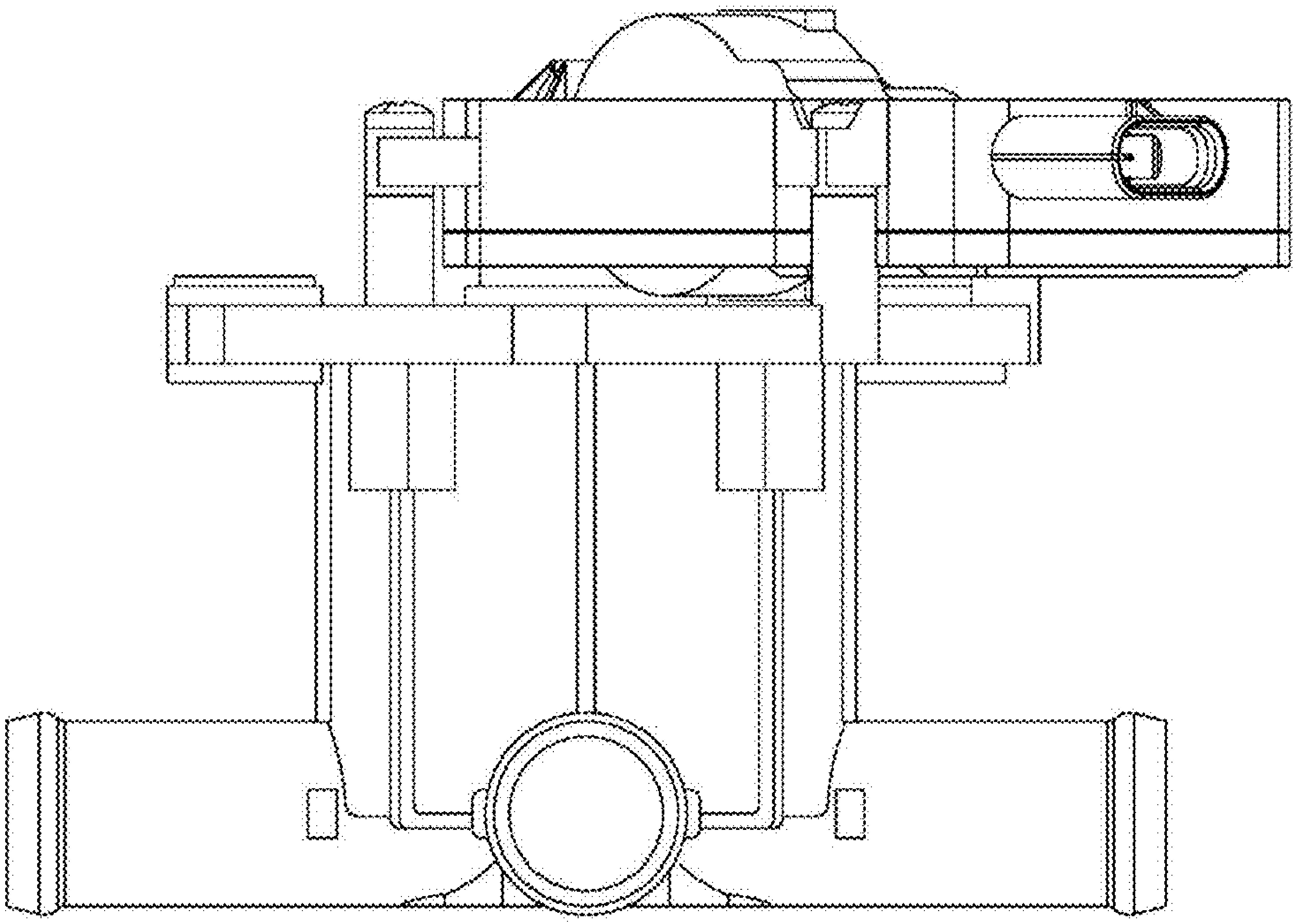


Fig. 3

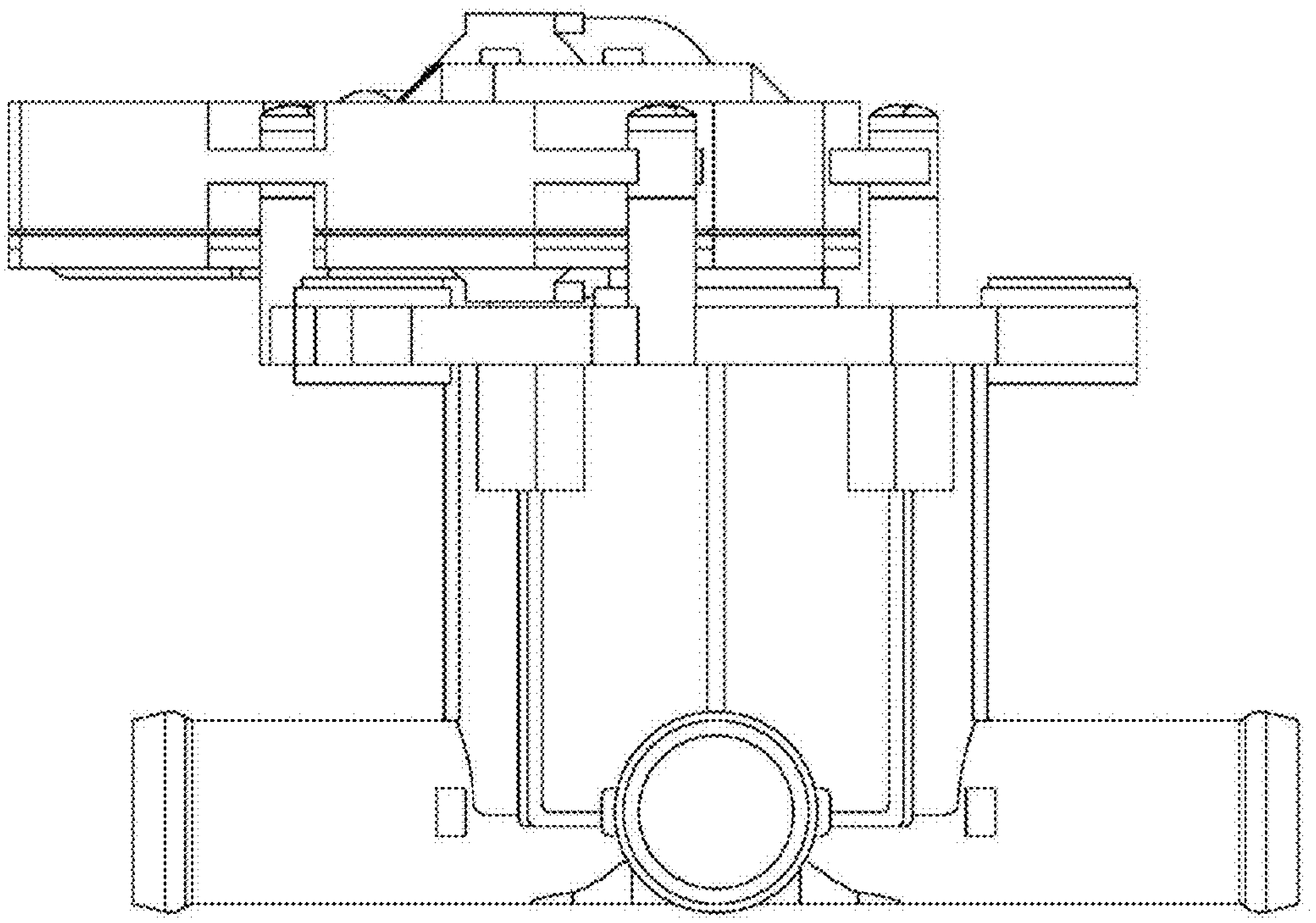


Fig. 4

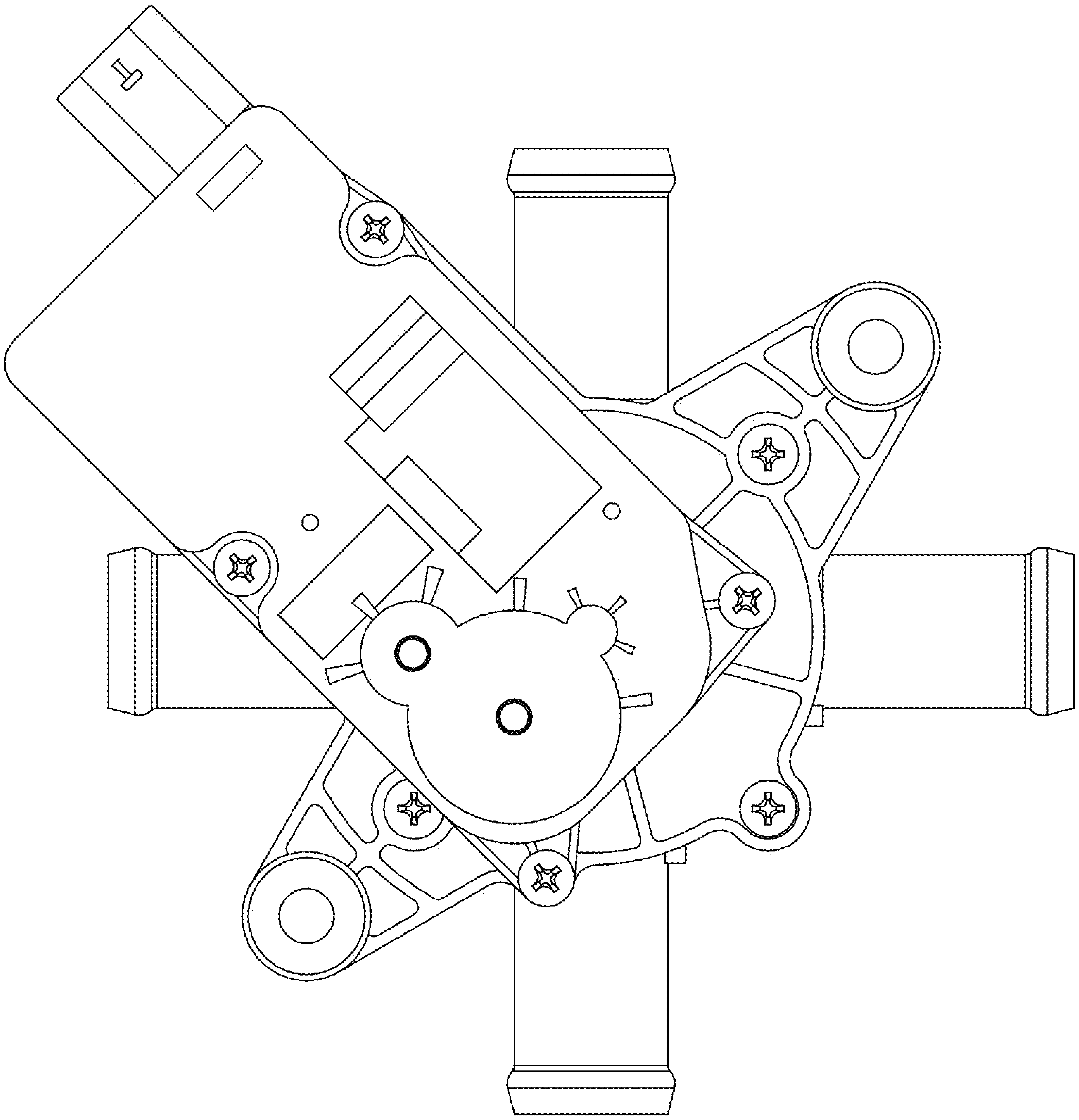


Fig. 5

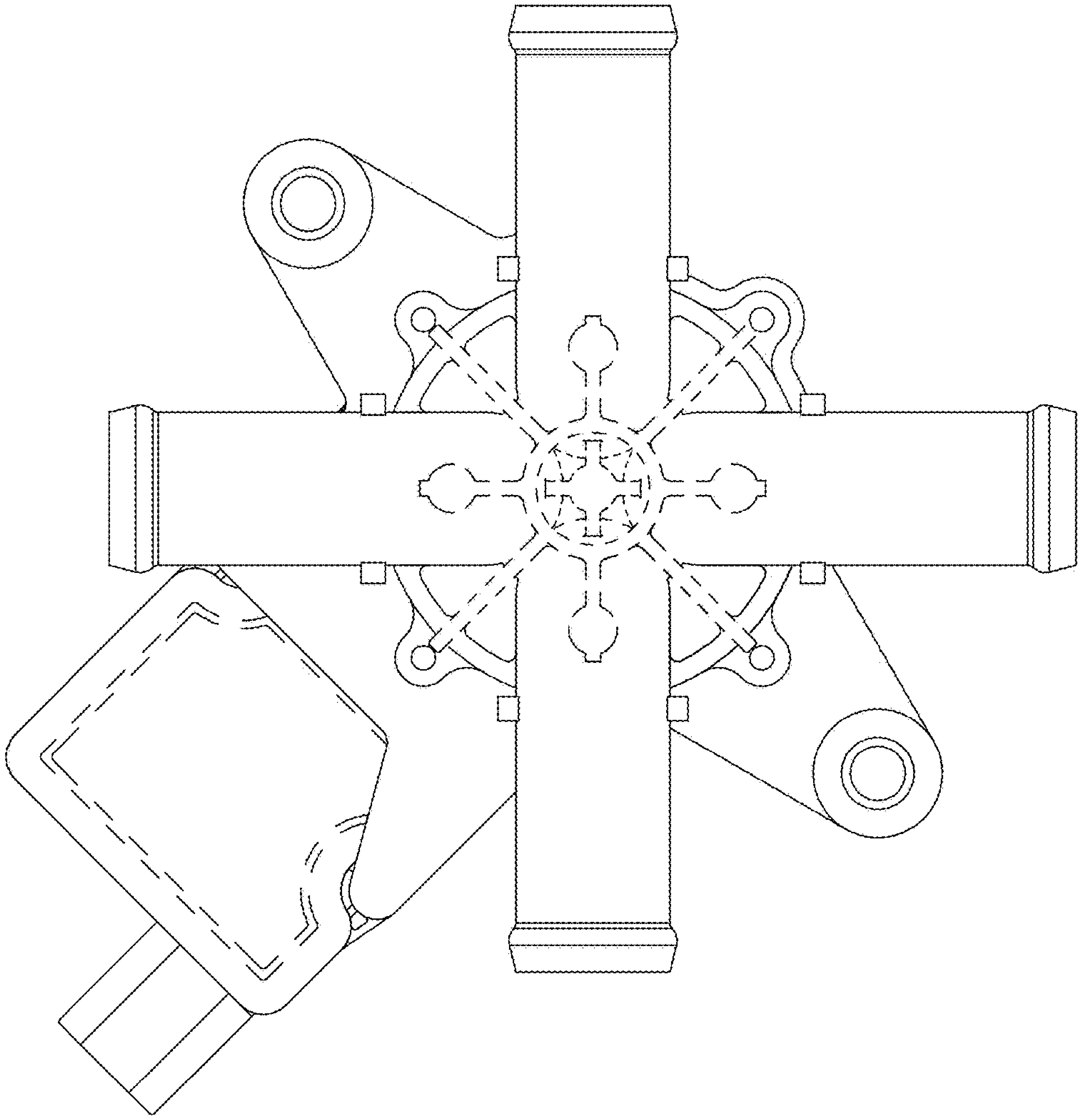


Fig. 6

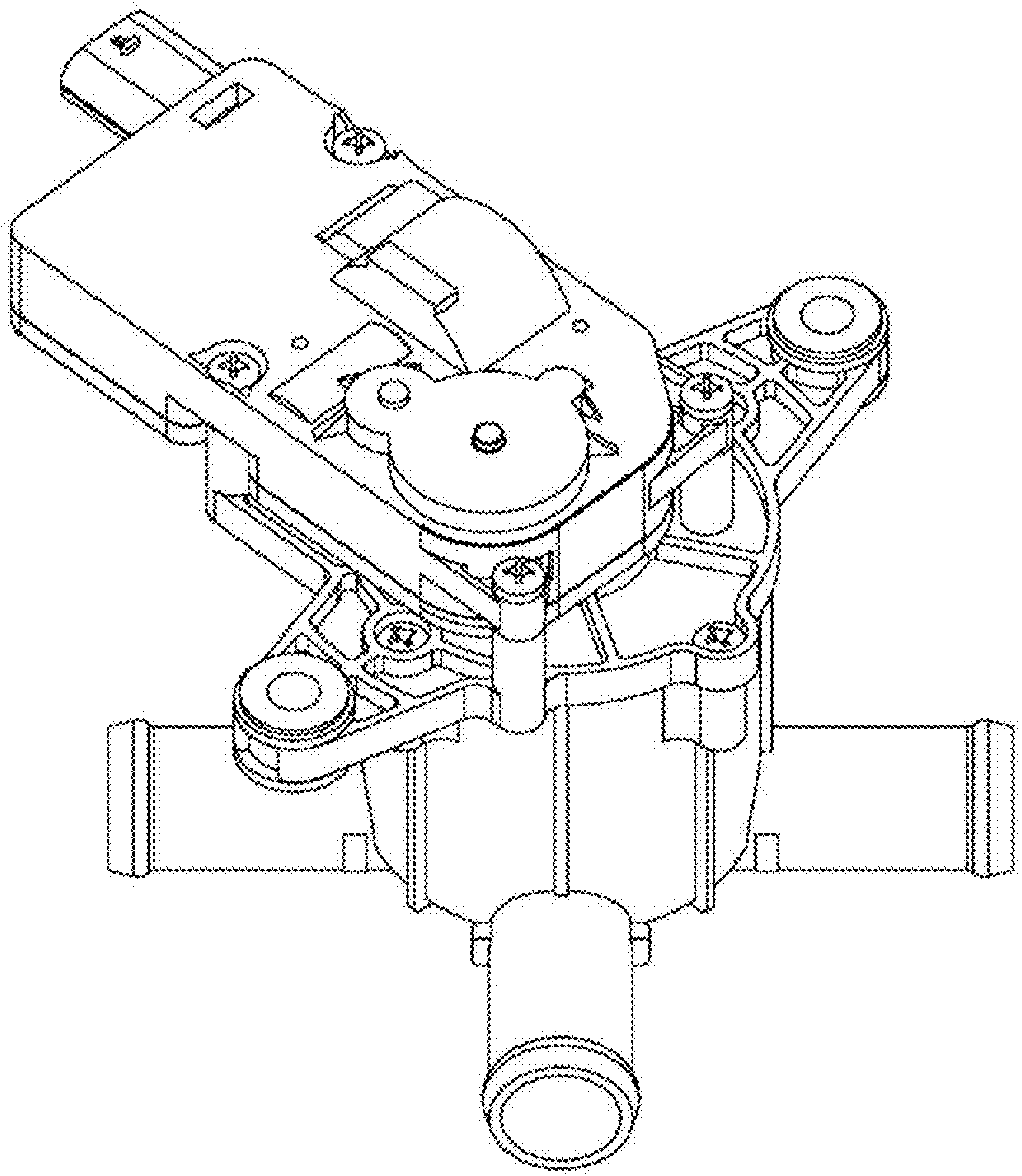


Fig. 7